

Dell EMC PowerEdge R6525

Technical Specifications

Notes, cautions, and warnings

 **NOTE:** A NOTE indicates important information that helps you make better use of your product.

 **CAUTION:** A CAUTION indicates either potential damage to hardware or loss of data and tells you how to avoid the problem.

 **WARNING:** A WARNING indicates a potential for property damage, personal injury, or death.

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Technical specifications

The technical and environmental specifications of your system are outlined in this section.

Topics:

- Chassis dimensions
- System weight
- Processor specifications
- PSU specifications
- Supported operating systems
- Cooling fan specifications
- System battery specifications
- Expansion card riser specifications
- Memory specifications
- Storage controller specifications
- Drive specifications
- Ports and connectors specifications
- Video specifications
- Environmental specifications

Chassis dimensions

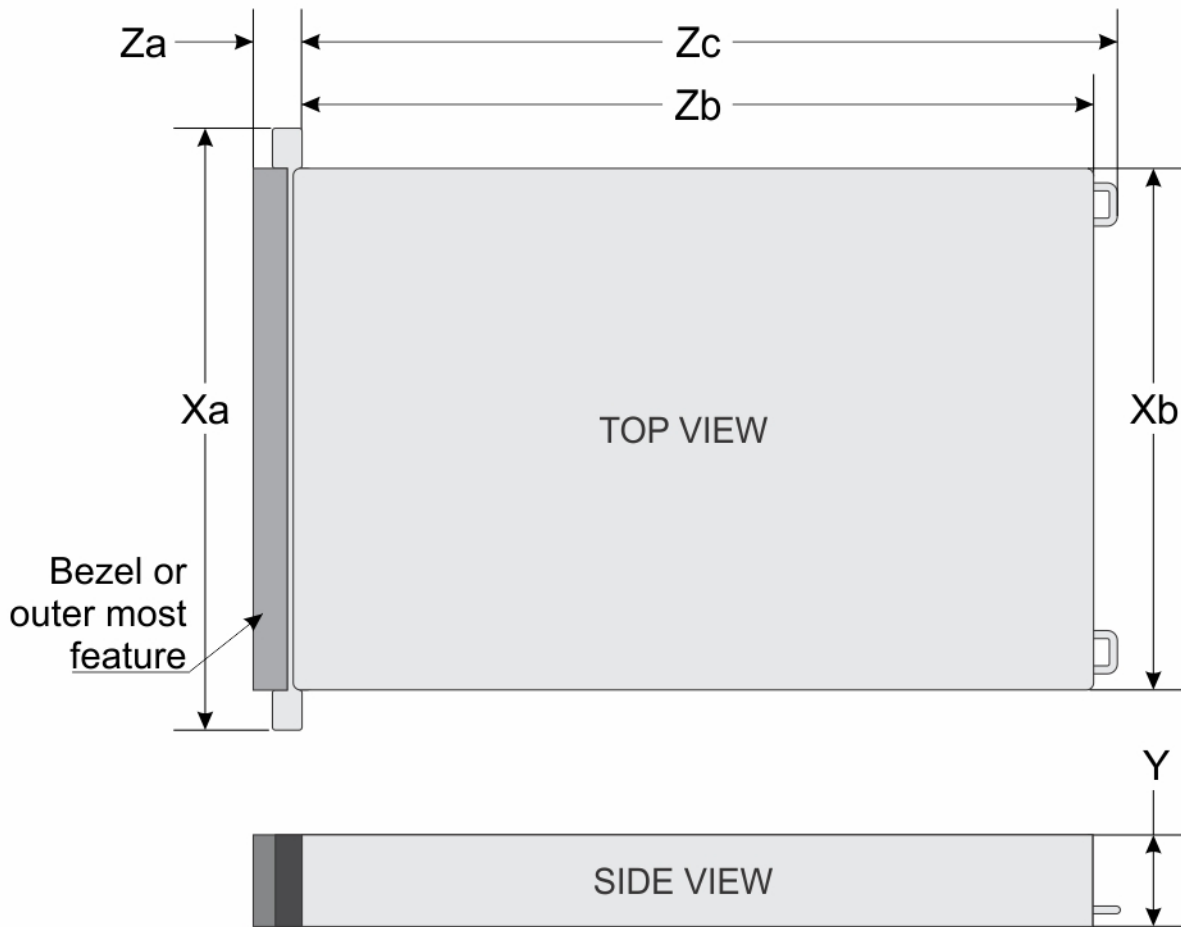


Figure 1. Chassis dimensions

Table 1. PowerEdge R6525 chassis dimensions

Drives	Xa	Xb	Y	Za	Zb*	Zc
Eight drives	482.0 mm (18.97 inches)	434.0 mm (17.08 inches)	42.8 mm (1.68 inches)	With bezel: 35.84 mm (1.4 inches) Without bezel: 22.0 mm (0.87 inches)	700.53 mm (27.58 inches) (Ear to rear wall)	736.27 mm (28.98 inches) (Ear to PSU handle)
Four or ten drives	482.0 mm (18.97 inches)	434.0 mm (17.08 inches)	42.8 mm (1.68 inches)	With bezel: 35.84 mm (1.4 inches) Without bezel: 22.0 mm (0.87 inches)	751.48 mm (29.58 inches) (Ear to I/O label)	787.05 mm (30.98 inches) (Ear to PSU handle)

NOTE: Zb* is the nominal rear wall external surface where the system board I/O connectors reside.

System weight

Table 2. PowerEdge R6525 system weight

System configuration	Maximum weight (with all drives/SSDs)
4 x 3.5-inch	21.8 kg (48.06 lb)
8 x 2.5-inch	19.2 kg (42.33 lb)
10 x 2.5-inch	21.8 kg (48.06 lb)

Processor specifications

Table 3. PowerEdge R6525 processor specifications

Supported processor	Number of processors supported
AMD EPYC 7002 or 7003 series processors	Two

PSU specifications

The PowerEdge R6525 system supports up to two AC or DC power supply units (PSUs).

⚠ WARNING: Instructions for the qualified electricians only:

System using -(48-60) V DC or 240 V DC power supplies are intended for restricted access locations in accordance with Articles 110-5, 110-6, 110-11, 110-14, and 110-17 of the National Electrical Code, American National Standards Institute (ANSI)/National Fire Protection Association (NFPA) 70.

240 V DC power supplies shall be connected to the 240 V DC outlet from certified power distribution units if applicable in country of use.

Power supply cords/jumper cords and the associated plugs/inlets/connectors shall have appropriate electrical ratings referencing the rating label on the system when used for connection.

Table 4. PowerEdge R6525 PSU specifications

PSU	Class (AC only)	Heat dissipation (maximum)	Frequency	Voltage	Current
800 W Mixed Mode	Platinum	3000 BTU/hr	50/60 Hz	100 -240 V AC	9.2 - 4.7 A
	N/A		DC	240 V DC	3.8 A
1100 W Mixed Mode	Titanium	4100 BTU/hr	50/60 Hz	100–240 V AC	12 A-6.3 A (X2)
	N/A		DC	240 V DC	5.2 A DC
1100 W (-48Vdc)	N/A	4265 BTU/hr	DC	(-48)-(-60) V DC	27 A
1400 W Mixed Mode	Platinum	5250 BTU/hr	50/60 Hz	100 - 240 V AC	12 - 8 A AC
	N/A		DC	240 V DC	6.6 A DC

ⓘ NOTE: When selecting or upgrading the system configuration, to ensure optimum power utilization, verify the system power consumption with the Dell Energy Smart Solution Advisor available at Dell.com/ESSA.

Supported operating systems

The PowerEdge R6525 supports the following operating systems:

- Canonical Ubuntu Server LTS

- Citrix XenServer
- Microsoft Windows Server with Hyper-V
- Red Hat Enterprise Linux
- SUSE Linux Enterprise Server
- VMware vSAN/ESXi

For more information, see www.dell.com/ossupport.

Cooling fan specifications

The PowerEdge R6525 system supports up to four standard (STD), high performance silver grade (HPR (Silver)), or high performance gold grade (HPR (Gold)) dual cooling fan modules.

Table 5. Cooling fan specifications

Fan type	Abbreviation	Also known as	Label color	Label image
Standard fan	STD	STD	No label	 <p>Figure 2. Standard fan</p>
High performance (Silver grade) fan	HPR (Silver)	HPR	Silver	<p>NOTE: New cooling fans comes with the High Performance Silver Grade label. While the older cooling fans has the High Performance label.</p>

Table 5. Cooling fan specifications (continued)


Fan type	Abbreviation	Also known as	Label color	Label image
				 <p data-bbox="772 1272 1150 1305">Figure 3. High performance fan</p>

Table 5. Cooling fan specifications (continued)

Fan type	Abbreviation	Also known as	Label color	Label image
				 <p data-bbox="770 1272 1326 1305">Figure 4. High performance (Silver grade) fan</p>
High performance (Gold grade) fan	HPR (Gold)	VHP - Very High Performance	Gold	<p data-bbox="770 1361 1469 1458">NOTE: New cooling fans comes with the High Performance Gold Grade label. While the older cooling fans has the High Performance label.</p>

Table 5. Cooling fan specifications (continued)

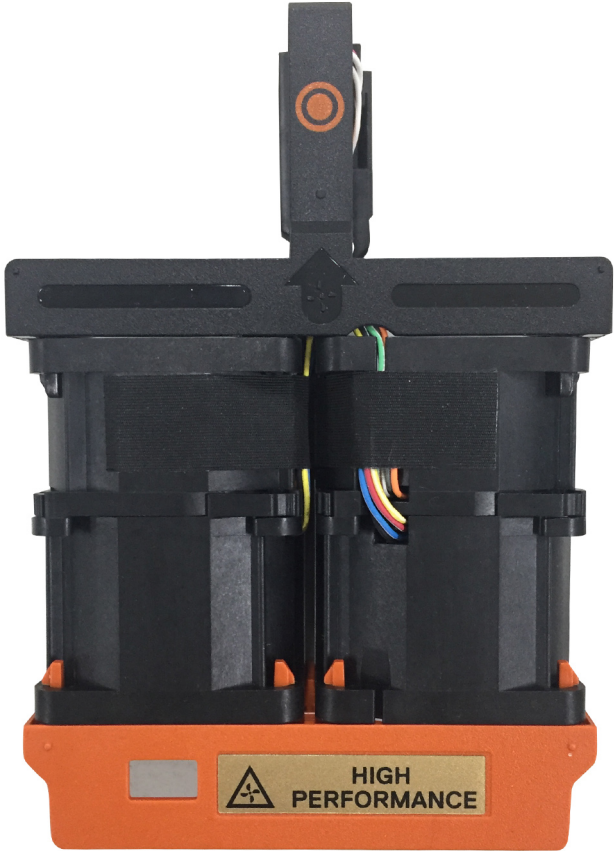
Fan type	Abbreviation	Also known as	Label color	Label image
				

Figure 5. High performance fan

Table 5. Cooling fan specifications (continued)

Fan type	Abbreviation	Also known as	Label color	Label image
				 <p data-bbox="772 1272 1310 1305">Figure 6. High performance (Gold grade) fan</p>

- NOTE:** You can distinguish between the High-performance (Silver) fan and High-performance (Gold) fan by the color of the label.
- NOTE:** Mixing of STD, HPR (Silver), or HPR (Gold) fan is not supported.
- NOTE:** The STD, HPR (Silver), or HPR (Gold) fan installation depends on the system configuration. For more information about the supported fan configuration or matrix, see [Thermal restriction matrix](#).

System battery specifications

The PowerEdge R6525 system supports CR 2032 3.0-V lithium coin cell system battery.

Expansion card riser specifications

WARNING: Consumer-Grade GPU should not be installed or used in the Enterprise Server products.

The PowerEdge R6525 system supports up to four PCI express (PCIe) Gen 4 expansion cards.

Table 6. Expansion card slots supported on the system board

PCIe slot	Risers	Riser width	PCIe slot height	PCIe slot length	Slot width
Slot 1	R2a (Riser 2)	x32 PCIe	Low profile	Half length	x16
Slot 1	R1a (Riser 1)	x16 PCIe	Full height	3/4th length	x16
Slot 2	R2a (Riser 2)	x32 PCIe	Low profile	Half length	x16
Slot 2	R4c + R4d (Riser 4)	x16 PCIe	Full height	3/4th length	x16
Slot 3	R3a (Riser 3)	x16 PCIe	Low profile	Half length	x16

Memory specifications

The PowerEdge R6525 system supports the following memory specifications for optimized operation.

Table 7. Memory specifications

DIMM type	DIMM rank	DIMM capacity	Single processor		Dual processor	
			Minimum RAM	Maximum RAM	Minimum RAM	Maximum RAM
RDIMM	Single rank	8 GB	8 GB	128 GB	16 GB	256 GB
	Dual rank	16 GB	16 GB	256 GB	32 GB	512 GB
		32 GB	32 GB	512 GB	64 GB	1 TB
		64 GB	64 GB	1 TB	128 GB	2 TB
LRDIMM	Quad rank	128 GB	128 GB	2 TB	256 GB	4 TB
	Octa rank	128 GB	128 GB	2 TB	256 GB	4 TB

NOTE: The older 32 GB capacity RDIMM memory with x4 data width and 8Gb DRAM density cannot be mixed with the newer 32 GB capacity RDIMM memory with x8 data width and 16Gb DRAM density in the same AMD EPYC™ processor unit.

NOTE: The older 128 GB capacity LRDIMM memory at 2666 MT/s speed cannot be mixed with the new 128 GB capacity LRDIMM memory at 3200 MT/s speed.

Table 8. Memory module sockets

Memory module sockets	Speed
32, 288-pin	3200 MT/s, 2933 MT/s, 2666 MT/s

Storage controller specifications

The PowerEdge R6525 system supports the following controller cards:

Table 9. PowerEdge R6525 system controller cards

Internal controllers	External controllers
<ul style="list-style-type: none"> PERC H755N PERC H745 HBA345 HBA355 S150 H345 	<ul style="list-style-type: none"> 12 Gbps SAS Ext. HBA PERC H840 HBA355E

Table 9. PowerEdge R6525 system controller cards

Internal controllers	External controllers
<ul style="list-style-type: none"> • Boot Optimized Storage Subsystem (BOSS-S1): HWRAID 2 x M.2 SSDs • Boot Optimized Storage Subsystem (BOSS-S2): HWRAID 2 x M.2 SSDs 	

- i NOTE:** The front PERC module for the PowerEdge R6525 system connects to the drive backplane. The front PERC module is connected in two different ways:
- Front mounting front PERC module
 - Rear mounting front PERC module

Drive specifications

Drives

The PowerEdge R6525 system supports:

- 4 x 3.5-inch hot-swappable SAS, SATA drives
- 8 x 2.5-inch hot-swappable SAS, SATA drives
- 10 x 2.5-inch hot-swappable SAS, SATA , or NVMe drives
- 10 + 2 x 2.5-inch hot-swappable SAS, SATA , or NVMe drives

Backplane:

- Up to 2 x 2.5-inch SAS, SATA, or NVMe drives
- Up to 4 x 3.5-inch SAS, SATA drives
- Up to 8 x 2.5-inch SAS, SATA drives
- Up to 10 x 2.5-inch SAS, SATA, or NVMe drives

- i NOTE:** For more information about how to hot swap NVMe PCIe SSD U.2 device, see the *Dell Express Flash NVMe PCIe SSD User's Guide* at <https://www.dell.com/support> **Browse all Products > Data Center Infrastructure > Storage Adapters & Controllers > Dell PowerEdge Express Flash NVMe PCIe SSD > Documentation > Manuals and Documents.**

Ports and connectors specifications

USB ports specifications

Table 10. PowerEdge R6525 system USB specifications

Front		Rear		Internal	
USB port type	No. of ports	USB port type	No. of ports	USB port type	No. of ports
USB 2.0-compliant port	One	USB 3.0-compliant ports	One	Internal USB 3.0-compliant port	One
Micro-USB 2.0 compliant port	One	USB 2.0-compliant ports	One		

- i NOTE:** The micro USB 2.0 compliant port can only be used as an iDRAC Direct or a management port.

- i NOTE:** The USB 2.0 specifications provide a 5 V supply on a single wire to power connected USB devices. A unit load is defined as 100 mA in USB 2.0, and 150 mA in USB 3.0. A device may draw a maximum of 5 unit loads (500 mA) from a port in USB 2.0; 6 (900 mA) in USB 3.0.

NOTE: The USB 2.0 interface can provide power to low-power peripherals but must adhere to USB specification. An external power source is required for higher-power peripherals to function, such as external CD/DVD Drives.

NIC port specifications

The PowerEdge R6525 system supports up to two 10/100/1000 Mbps Network Interface Controller (NIC) ports embedded on the LAN on Motherboard (LOM) and integrated on the optional OCP cards.

Table 11. NIC port specification

Feature	Specifications
LOM card	1 GB x 2
OCP card (OCP 3.0)	1 GbE x 4, 10 GbE x 2, 25 GbE x 2, 25 GbE x 4, 50 GbE x 2, 100 GbE x 2

Serial connector specifications

The PowerEdge R6525 system supports one optional card type serial connector, which is a 9-pin connector, Data Terminal Equipment (DTE), 16550-compliant.

The optional serial connector card is installed similar to an expansion card filler bracket.

VGA ports specifications

The PowerEdge R6525 system supports one DB-15 VGA port that is located on the front and rear panel of the system.

IDSDM

The PowerEdge R6525 system supports optional Internal Dual SD module (IDSDM).

The IDSDM supports two SD cards and is available in the following configurations:

Table 12. Supported SD card storage capacity

IDSDM card
<ul style="list-style-type: none">16 GB32 GB64 GB

NOTE: One IDSDM card slot is dedicated for redundancy.

NOTE: Use Dell EMC branded SD cards that are associated with the IDSDM configured systems.

Video specifications

The PowerEdge R6525 system supports integrated Matrox G200 graphics controller with 16 MB of video frame buffer.

Table 13. Supported front video resolution options

Resolution	Refresh rate (Hz)	Color depth (bits)
1024 x 768	60	8, 16, 32
1280 x 800	60	8, 16, 32
1280 x 1024	60	8, 16, 32

Table 13. Supported front video resolution options (continued)

Resolution	Refresh rate (Hz)	Color depth (bits)
1360 x 768	60	8, 16, 32
1440 x 900	60	8, 16, 32
1600 x 900	60	8, 16, 32
1600 x 1200	60	8, 16, 32
1680 x 1050	60	8, 16, 32
1920 x 1080	60	8, 16, 32
1920 x 1200	60	8, 16, 32

Table 14. Supported rear video resolution options

Resolution	Refresh rate (Hz)	Color depth (bits)
1024 x 768	60	8, 16, 32
1280 x 800	60	8, 16, 32
1280 x 1024	60	8, 16, 32
1360 x 768	60	8, 16, 32
1440 x 900	60	8, 16, 32
1600 x 900	60	8, 16, 32
1600 x 1200	60	8, 16, 32
1680 x 1050	60	8, 16, 32
1920 x 1080	60	8, 16, 32
1920 x 1200	60	8, 16, 32

Environmental specifications


 **NOTE:** For additional information about environmental certifications, refer to the *Product Environmental Datasheet* located with the Manuals & Documents on www.dell.com/support/home.

Table 15. Operational climatic range category A2

Temperature	Specifications
Allowable continuous operations	
Temperature ranges for altitudes <= 900 m (<= 2953 ft)	10–35°C (50–95°F) with no direct sunlight on the equipment
Humidity percent ranges (non-condensing at all times)	8% RH with -12°C minimum dew point to 80% RH with 21°C (69.8°F) maximum dew point
Operational altitude de-rating	Maximum temperature is reduced by 1°C/300 m (1.8°F/984 Ft) above 900 m (2953 Ft)

Table 16. Operational climatic range category A3

Temperature	Specifications
Allowable continuous operations	
Temperature ranges for altitudes <= 900 m (<= 2953 ft)	5–40°C (41–104°F) with no direct sunlight on the equipment

Table 16. Operational climatic range category A3 (continued)

Temperature	Specifications
Humidity percent ranges (non-condensing at all times)	8% RH with -12°C minimum dew point to 85% RH with 24°C (75.2°F) maximum dew point
Operational altitude de-rating	Maximum temperature is reduced by 1°C/175 m (1.8°F/574 Ft) above 900 m (2953 Ft)

Table 17. Operational climatic range category A4

Temperature	Specifications
Allowable continuous operations	
Temperature ranges for altitudes <= 900 m (<= 2953 ft)	5–45°C (41–113°F) with no direct sunlight on the equipment
Humidity percent ranges (non-condensing at all times)	8% RH with -12°C minimum dew point to 90% RH with 24°C (75.2°F) maximum dew point
Operational altitude de-rating	Maximum temperature is reduced by 1°C/125 m (1.8°F/410 Ft) above 900 m (2953 Ft)

Table 18. Shared requirements across all categories


Temperature	Specifications
Allowable continuous operations	
Maximum temperature gradient (applies to both operation and non-operation)	20°C in an hour* (36°F in an hour) and 5°C in 15 minutes (9°F in 15 minutes), 5°C in an hour* (9°F in an hour) for tape hardware  NOTE: * - Per ASHRAE thermal guidelines for tape hardware, these are not instantaneous rates of temperature change.
Non-operational temperature limits	-40 to 65°C (-40 to 149°F)
Non-operational humidity limits	5% to 95% RH with 27°C (80.6°F) maximum dew point
Maximum non-operational altitude	12,000 meters (39,370 feet)
Maximum operational altitude	3,048 meters (10,000 feet)

Table 19. Maximum vibration specifications

Maximum vibration	Specifications
Operating	0.21 G _{rms} at 5 Hz to 500 Hz (all operation orientations)
Storage	1.88 G _{rms} at 10 Hz to 500 Hz for 15 minutes (all six sides tested)

Table 20. Maximum shock pulse specifications

Maximum shock pulse	Specifications
Operating	Six consecutively executed shock pulses in the positive and negative x, y, and z axis of 6 G for up to 11 ms.
Storage	Six consecutively executed shock pulses in the positive and negative x, y, and z axis (one pulse on each side of the system) of 71 G for up to 2 ms.

Thermal air restrictions

ASHRAE A3 environment

- CPU TDP equal or greater than 180 W are not supported.
- Rear drives are not supported.

- 128 GB or greater capacity LRDIMMs are not supported.
- Two PSUs are required in redundant mode, however PSU failure is not supported.
- Non-Dell qualified peripheral cards and/or peripheral cards greater than 25 W are not supported.
- GPU is not supported.
- BOSS 1.5 is not supported.
- NVMe is not supported.

ASHRAE A4 environment

- CPU TDP equal or greater than 155 W are not supported.
- Rear drives are not supported.
- 128 GB or greater capacity LRDIMMs are not supported.
- Two PSUs are required in redundant mode, however PSU failure is not supported.
- Non-Dell qualified peripheral cards and/or peripheral cards greater than Tier 5 cards are not supported.
- GPU is not supported.
- BOSS 1.5 is not supported.
- OCP 3.0 card cooling tier greater than Tier4 is not supported.
- NVMe is not supported.

Liquid cooling: ASHRAE A3 environment

- 128 GB or greater capacity LRDIMMs are not supported.
- Two PSUs are required in redundant mode, but PSU failure is not supported.
- Non Dell qualified peripheral cards and/or peripheral cards greater than 25 W are not supported.
- GPU is not supported.
- BOSS 1.5 is not supported.
- NVMe is not supported.

Liquid cooling: ASHRAE A4 environment

- Rear drives are not supported.
- 128 GB or greater capacity LRDIMMs are not supported.
- Two PSUs are required in redundant mode, but PSU failure is not supported.
- Non Dell qualified peripheral cards and/or peripheral cards greater than Tier 5 are not supported.
- OCP 3.0 card cooling tier greater than Tier 4 is not supported.
- GPU is not supported.
- BOSS 1.5 is not supported.
- NVMe is not supported.

Thermal restriction matrix

Table 21. Thermal restriction matrix

Configuration		4 x 3.5-inch			8 x 2.5-inch		10 x 2.5-inch SAS			10 x 2.5-inch NVMe	
Rear configuration		3 LP/ 2 FH	Rear 2 x 2.5-inch SAS	Rear 2 x 2.5-inch NVMe	3 LP/ 2 FH	Rear 2 x 2.5-inch NVMe(single processor)	3 LP/ 2 FH	Rear 2 x 2.5-inch SAS	Rear 2 x 2.5-inch NVMe	3 LP/ 2 FH	Rear 2 x 2.5-inch NVMe
CPU TDP	CPU cTDP Max										
120 W	150 W	STD fan	HPR Fan	HPR Fan	STD fan	HPR Fan	VHP fan	VHP fan	VHP fan	VHP fan	VHP fan

Table 21. Thermal restriction matrix (continued)

Configuration		4 x 3.5-inch			8 x 2.5-inch		10 x 2.5-inch SAS			10 x 2.5-inch NVMe	
Rear configuration		3 LP/ 2 FH	Rear 2 x 2.5-inch SAS	Rear 2 x 2.5-inch NVMe	3 LP/ 2 FH	Rear 2 x 2.5-inch NVMe (single processor)	3 LP/ 2 FH	Rear 2 x 2.5-inch SAS	Rear 2 x 2.5-inch NVMe	3 LP/ 2 FH	Rear 2 x 2.5-inch NVMe
CPU TDP	CPU cTDP Max										
		STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK	STD HSK
155 W	180 W	STD fan STD HSK	HPR Fan STD HSK	HPR Fan STD HSK	STD fan STD HSK	HPR Fan STD HSK	VHP fan STD HSK	VHP fan STD HSK	VHP fan STD HSK	VHP fan STD HSK	VHP fan STD HSK
180 W	200 W	HPR fan L-type HSK	HPR Fan L-type HSK	HPR Fan L-type HSK	HPR fan L-type HSK	HPR Fan L-type HSK	VHP fan L-type HSK	VHP fan L-type HSK	VHP fan L-type HSK	VHP fan L-type HSK	VHP fan L-type HSK
200 W	200 W	HPR fan L-type HSK	HPR Fan L-type HSK	HPR Fan L-type HSK	HPR fan L-type HSK	HPR Fan L-type HSK	VHP fan L-type HSK	VHP fan L-type HSK	VHP fan L-type HSK	VHP fan L-type HSK	VHP fan L-type HSK
225 W	240 W	HPR fan L-type HSK	HPR Fan L-type HSK	HPR Fan L-type HSK	HPR fan L-type HSK	HPR Fan L-type HSK	VHP fan L-type HSK	VHP fan L-type HSK	VHP fan L-type HSK	VHP fan L-type HSK	VHP fan L-type HSK
280 W - 64C (7H12,7763)		HPR fan* L-type HSK	HPR Fan* L-type HSK	HPR Fan* L-type HSK	HPR fan L-type HSK	HPR Fan* L-type HSK	VHP fan* L-type HSK	VHP fan* L-type HSK	VHP fan* L-type HSK	VHP fan L-type HSK	VHP fan* L-type HSK
280 W - 32C (75F3)		-	-	-	VHP fan* L-type HSK	-	VHP fan* L-type HSK	-	-	VHP fan* L-type HSK	-
280 W - 64C/32C/24C 280 W (7773X,7573X,7473X)		-	-	-	-	-	VHP fan L-type HSK	VHP fan* L-type HSK	VHP fan* L-type HSK	-	-
280 W - 16C 280 W (7373X)		-	-	-	-	-	VHP fan** L-type HSK	-	-	-	-
T4 or A2 GPU		HPR fan*	HPR Fan*	HPR Fan*	HPR fan*	-	VHP fan*	VHP fan*	VHP fan*	VHP fan*	VHP fan*

NOTE: * Supported ambient temperature is 30°C.

NOTE: ** Supported ambient temperature is 25°C.

Table 22. Liquid cooling thermal restriction matrix

Configuration		4 x 3.5-inch			8 x 2.5-inch	10 x 2.5-inch SAS			10 x 2.5-inch NVMe	
Rear storage		3 LP/ 2 FH	Rear 2 x 2.5-inch SAS	Rear 2 x 2.5-inch NVMe	3 LP/ 2 FH	3 LP/ 2 FH	Rear 2 x 2.5-inch SAS	Rear 2 x 2.5-inch NVMe	3 LP/ 2 FH	Rear 2 x 2.5-inch NVMe
CPU TDP	CPU cTDP Max									
120 W	150 W	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan
155 W	180 W	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan
180 W	200 W	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan
200 W	200 W	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan
225 W	240 W	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan
280 W	280 W	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan
T4 GPU		HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan	HPR fan

NOTE: Three dual fan modules are required for single processor, and four dual fan modules are required for dual processor system.

NOTE: For T4 GPU and 280 W CPU, maximum supported ambient temperature is 30°C. For other configurations maximum supported ambient temperature is 35°C.

Table 23. Processor and heat sink matrix

Heat sink	Processor TDP
STD HSK	< 180 W
L-type HSK	Processor 1 >= 180 W
L-type HSK	Processor 2 >= 180 W

Table 24. Processor support matrix

Processor	TDP (W)	cTDP Max (W)	Cores	Heat sink (HSK) type	Fan type (x4/x8)	Fan type (x10)	Support A3	Support A4
7773X	280	280	64	L-type HSK	NA	HPR (gold) fan	No	No
7573X	280	280	32	L-type HSK	NA	HPR (gold) fan	No	No
7H12	280	280	64	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7F72	240	240	24	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7F52	225	240	16	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7662	225	240	64	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7643	240	240	56	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No

Table 24. Processor support matrix (continued)

Processor	TDP (W)	cTDP Max (W)	Cores	Heat sink (HSK) type	Fan type (x4/x8)	Fan type (x10)	Support A3	Support A4
7742	225	240	64	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7713P	225	240	64	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7642	225	240	48	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7552	200	200	48	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7702	200	200	64	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7663	240	240	56	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7543P	225	240	32	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7542	225	240	32	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7532	200	200	32	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7F32	180	180	8	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7513	200	200	32	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7502	180	200	32	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
74F3	240	240	24/48	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7402	180	200	24	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7452	155	180	32	STD HSK	STD fan	HPR (gold) fan	Yes	No
7443P	200	200	24	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7443	200	200	24	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7352	155	180	24	STD HSK	STD fan	HPR (gold) fan	Yes	No
7343	200	200	32	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7313P	155	180	16	STD HSK	STD fan	HPR (gold) fan	Yes	No
7302	155	180	16	STD HSK	STD fan	HPR (gold) fan	Yes	No
72F3	180	200	8	L-type HSK	HPR (silver) fan	HPR (gold) fan	No	No
7282	120	150	16	STD HSK	STD fan	HPR (gold) fan	Yes	Yes

Table 24. Processor support matrix (continued)

Processor	TDP (W)	cTDP Max (W)	Cores	Heat sink (HSK) type	Fan type (x4/x8)	Fan type (x10)	Support A3	Support A4
7272	120	150	12	STD HSK	STD fan	HPR (gold) fan	Yes	Yes
7252	120	150	8	STD HSK	STD fan	HPR (gold) fan	Yes	Yes
7262	155	180	8	STD HSK	STD fan	HPR (gold) fan	Yes	No

NOTE: DIMM blanks are required on empty slots if 280 W CPU is installed.

NOTE: Processors 7573X and 7773X support only x10 SAS/SATA drives.

Table 25. T4 GPU support restriction

Rear Config	2.5-inch x 10		2.5-inch x 8		3.5-inch x 4	
	3 x LP	2 x FH	3 x LP	2 x FH	3 x LP	2 x FH
Slot 1	Supported	Supported	Supported	Supported	Supported	Supported
Slot 2	Supported	Supported	Supported	Supported	Supported	Supported
Slot 3	Supported	NA	Not supported	NA	Not supported	NA

NOTE: 128 GB LRDIMM 3200 MT/s or higher memory is not supported with 280 W T4/A2 configuration.

Table 26. Label reference

Label	Description
STD	Standard
HPR	High performance (silver grade)
VHP	Very high performance (gold grade)
HSK	Heat sink
LP	Low profile
FH	Full height